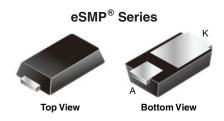
AUTOMOTIVE



## Vishay General Semiconductor

# Surface-Mount TMBS® (Trench MOS Barrier Schottky) Rectifier



#### MicroSMP (DO-219AD)



#### **LINKS TO ADDITIONAL RESOURCES**



PRIMARY CHARACTERISTICS			
I <sub>F(AV)</sub>	1.0 A		
$V_{RRM}$	200 V		
I <sub>FSM</sub>	25 A		
V <sub>F</sub> at I <sub>F</sub> = 1.0 A (125 °C)	0.65 V		
T <sub>J</sub> max.	175 °C		
Package	MicroSMP (DO-219AD)		
Circuit configuration	Single		

#### **FEATURES**

• Very low profile - typical height of 0.65 mm



· Low forward voltage drop

• Low power loss, high efficiency

 Meets MSL level 1, per LF maximum peak of 260 °C

RoHS COMPLIANT J-STD-020, HALOGEN FREE

• AEC-Q101 qualified available

Automotive ordering code: base P/NHM3

• Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

#### **TYPICAL APPLICATIONS**

For use in low voltage high frequency inverters, freewheeling, DC/DC converters, and polarity protection applications, in commercial, industrial, and automotive applications.

#### **MECHANICAL DATA**

Case: MicroSMP (DO-219AD)

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, and RoHS-compliant

Base P/NHM3 - halogen-free, RoHS-compliant, and

AEC-Q101 qualified

Terminals: matte tin plated leads, solderable per

J-STD-002 and JESD 22-B102

M3 and HM3 suffix meets JESD 201 class 2 whisker test

Polarity: color band denotes the cathode end

MAXIMUM RATINGS (T <sub>A</sub> = 25 °C unless otherwise noted)					
PARAMETER	SYMBOL	V1P22	UNIT		
Device marking code		V1D			
Maximum repetitive peak reverse voltage	$V_{RRM}$	200	V		
Maximum DC reverse voltage	$V_{DC}$	160	V		
Maximum average forward rectified current	I <sub>F(AV)</sub> (1)	1.0	Α		
Peak forward surge current 10 ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	25	Α		
Operating junction temperature range	T <sub>J</sub> <sup>(2)</sup>	-40 to +175	°C		
Storage temperature range	T <sub>STG</sub>	-55 to +175	°C		

#### Notes

(1) Free air mounted on recommended copper pad area

 $^{(2)}$  The heat generated must be less than the thermal conductivity from junction to ambient:  $dP_D/dT_J < 1/R_{0JA}$ 



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<b>ELECTRICAL CHARACTERISTICS</b> (T <sub>A</sub> = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	I <sub>F</sub> = 0.5 A	T <sub>A</sub> = 25 °C	V <sub>F</sub> <sup>(1)</sup>	0.74	-	V
	I <sub>F</sub> = 1.0 A			0.80	0.88	
	$I_F = 0.5 A$	T <sub>A</sub> = 125 °C		0.58	-	
	I <sub>F</sub> = 1.0 A			0.65	0.73	
Reverse current	V <sub>R</sub> = 160 V	T <sub>A</sub> = 25 °C	I <sub>R</sub> <sup>(2)</sup>	0.001	-	- mA
	V <sub>R</sub> = 100 V	T <sub>A</sub> = 125 °C		0.1	-	
	V <sub>R</sub> = 200 V	T <sub>A</sub> = 25 °C		-	0.015	
		T <sub>A</sub> = 125 °C		0.2	1.0	
Typical junction capacitance	4.0 V, 1 MHz		CJ	50.0	-	pF

#### Notes

 $^{(1)}\,$  Pulse test: 300  $\mu s$  pulse width, 1 % duty cycle

(2) Pulse test: pulse width ≤ 5 ms

THERMAL CHARACTERISTICS (T <sub>A</sub> = 25 °C unless otherwise noted)				
PARAMETER	SYMBOL	V1P22		
Typical thermal resistance	R <sub>0</sub> JA (1)(2)	130	°C/W	
	R <sub>0JM</sub> (3)	20	J 0/VV	

#### Notes

- (1) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$
- $^{(2)}$  Free air, mounted on recommended copper pad area; thermal resistance,  $R_{\theta JA}$  junction to ambient
- $^{(3)}$  Mounted on recommended copper pad area; thermal resistance,  $R_{\theta JM}$  junction to mount

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
V1P22-M3/H	0.006	Н	4500	7" diameter plastic tape and reel
V1P22HM3/H (1)	0.006	Н	4500	7" diameter plastic tape and reel

#### Note

(1) AEC-Q101 qualified



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## **RATINGS AND CHARACTERISTICS CURVES** ( $T_A = 25$ °C unless otherwise noted)

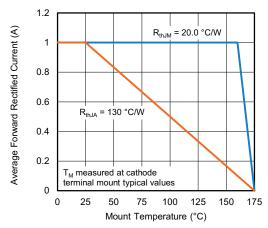


Fig. 1 - Maximum Forward Current Derating Curve

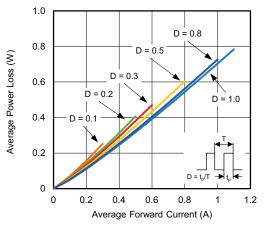


Fig. 2 - Average Power Loss Characteristics

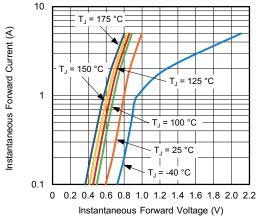


Fig. 3 - Typical Instantaneous Forward Characteristics

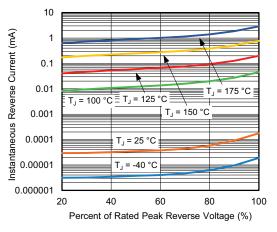


Fig. 4 - Typical Reverse Leakage Characteristics

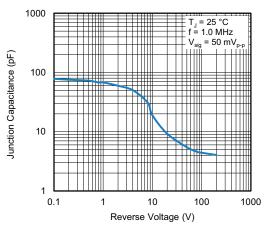


Fig. 5 - Typical Junction Capacitance

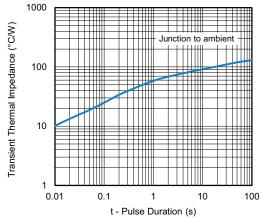
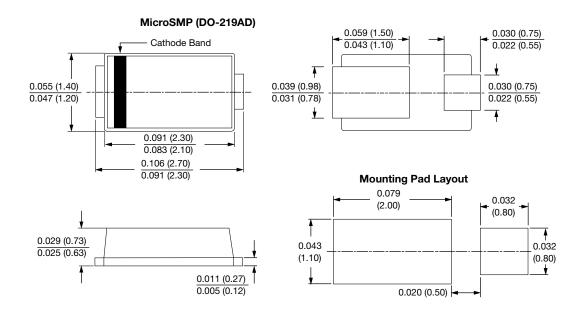


Fig. 6 - Typical Transient Thermal Impedance



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#### **PACKAGE OUTLINE DIMENSIONS** in inches (millimeters)





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